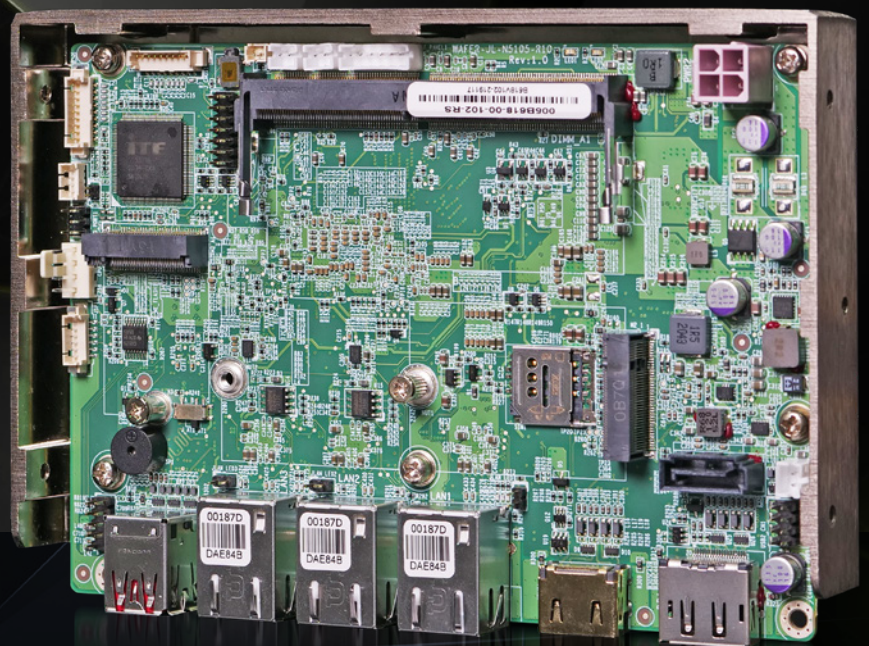
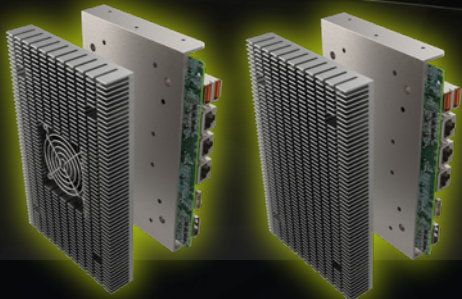


WAFER-JL-N5105

Intel® Celeron® N5105 powered 3.5" embedded board

- Intel® Celeron® N5105 on-board SoC, 4 cores and 4 threads, 2.00GHz base frequency
- Three Intel® I225V 2.5GbE ports
- Two USB 3.2 Gen 2, two USB 2.0, two RS-232
- M.2 A key and M.2 B key expansions
- Support dual independent display via HDMI and DP

Excellent Thermal Solution



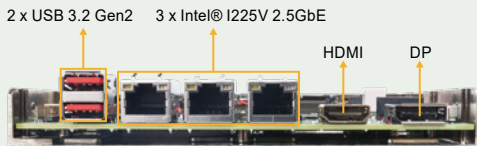
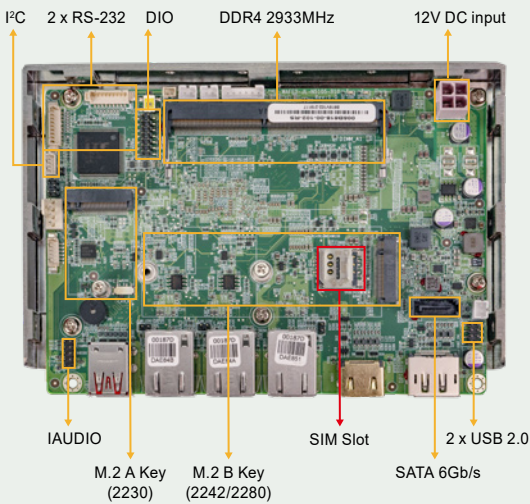
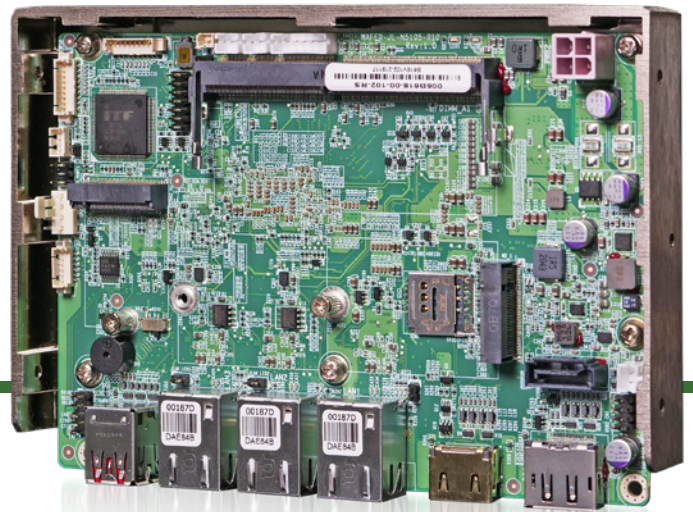
iei®



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WAFER-JL-N5105

ATX motherboard supports 10th/11th Generation Intel® Core™ i9/i7/i5/i3, Celeron® and Pentium® processor, DDR4 memory, triple independent display, dual 2.5GbE LAN, M.2, USB 3.2, SATA 6Gb/s, HD Audio and RoHS



Advanced Jasper Lake Platform



The new generation of Intel ultra-low power processor, the Jasper Lake series, is built with the new 10nm process and Tremont architecture, and integrated with 11th gen Intel® UHD Graphics.

10W Low-power Intel® Celeron® N5105 CPU



10nm Intel® Celeron® N5105 on-board SoC features 4 cores, 4 threads, 2.0GHz base frequency, up to 2.9GHz turbo frequency and 4MB cache.

Supporting Intel® I225V 2.5GbE Controllers



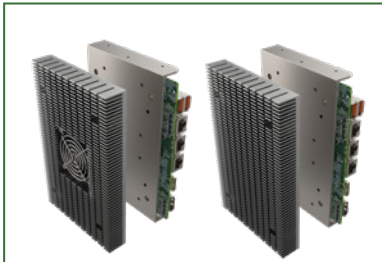
Three RJ45 network interfaces are supported via Intel® I225V 2.5GbE controllers, achieving up to 2.5GbE network transmission rate

Rich I/O Interface



The WAFER-JL supports two external USB 3.2 Gen 2 (10Gb/s) ports, providing lightning-fast data transfer rate. The internal USB 2.0 ports, M.2 A key slot and M.2 B key slot can be used for function expansion.

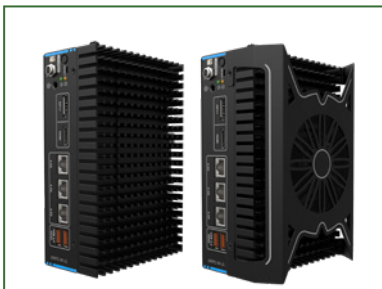
Structure Solution



IEI Heat Conduction Casing (IHCC)

IEI has developed a highly efficient thermal solution for the 3.5" motherboard - IEI Heat Conduction Casing (IHCC). With its well-design structure, the IHCC can effectively improve heat transfer performance and cut time-to-market.

Completely joint with CPU for better heat transfer in 0°C~60°C operating temperature with the active cooling (PN:CM-WAFER-WF-R10), and in 0°C~45°C operating temperature with the passive cooling (PN:CM-WAFER-WOF-R10).



DRPC-W-JL-R10

The DRPC-W-JL-R10 is a compact embedded system and designed for 3.5" single board computers . With the two-dimensional heat conduction and low wind resistance design on the surfaced which means you don't need extra thermal solution to form the heat dissipation part. You can get higher hardness, and benefit from the reduced production cost resulting from shortening manufacturing time .Furthermore, the height of aluminum extrusion can therefore be downsized to make the product light weight.



WAFER-JL-N5105 Block Diagram

